

Product Change Notification - RMES-09VPXZ131 (Printer Friendly)

Date: 28 Apr 2017
Product Category: Ethernet PHYs
Notification subject: CCB 2922 Initial Notice: Qualification of ASEK as an additional assembly site for selected products of the 0.18 wafer technology at DBHU available in 48L TQFP package using gold (Au) bond wire.
Notification text: **PCN Status:**
Initial notification.

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of ASEK as an additional assembly site for selected products of the 0.18 wafer technology at DBHU available in 48L TQFP package using gold (Au) bond wire.

Pre Change:

Assembled at TICP using gold (Au) bond wire and CEL9200 molding compound material.

Post Change:

Assembled at ASEK using gold (Au) bond wire and G631H molding compound material.

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	TICP	ASEK
Lead frame material	C7025	C7025
Wire material	Au	Au
Die attach material	EN4900	CRM-1076WA
Mold compound material	CEL9200	G631H

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve productivity by qualifying ASEK as an additional assembly site.

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

September 2017

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	April 2017				->	September 2017				
Workweek	14	15	16	17		35	36	37	38	39
Initial PCN Issue Date				X						
Qual Report Availability										X
Final PCN Issue Date										X

Method to Identify Change:

Traceability code

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN_#_Qual Plan.

Revision History:

April 28, 2017: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_RMES-09VPXZ131_Affected_CPN.pdf](#) [PCN_RMES-09VPXZ131Qual_Plan.pdf](#)
[PCN_RMES-09VPXZ131_Affected_CPN.xlsx](#)

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Affected Catalog Part Number (CPN)

PCN_RMES-09VPXZ131
CATALOG_PART_NBR
KSZ8041FTL
KSZ8041FTLI
KSZ8041FTLI-TR
KSZ8041FTL-S
KSZ8041FTL-TR
KSZ8041TL
KSZ8041TLI
KSZ8041TLI-S
KSZ8041TLI-TR
KSZ8041TL-TR
SPNY801037
SPNY801037-TR
SPNY801049
SPNY801049-TR
SPNY801051
SPNY801051-TR
SPNY801066
SPNY801066-TR
SPNY801087
SPNY801087-TR
SPNZ801037
SPNZ801037-TR
SPNZ801049
SPNZ801049-TR
SPNZ801051
SPNZ801051-TR
SPNZ801053
SPNZ801053-TR
SPNZ801056
SPNZ801057
SPNZ801066
SPNZ801066-TR
SPNZ801087
SPNZ801087-TR



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QUALIFICATION PLAN SUMMARY

PCN #: RMES-09VPXZ131

**Date:
April 10, 2017**

Qualification of ASEK as an additional assembly site for selected products of the 0.18 wafer technology at DBHU available in 48L TQFP package using gold (Au) bond wire.

Purpose: _____ Qualification of ASEK as an additional assembly site for selected products of the 0.18 wafer technology at DBHU available in 48L TQFP package using gold (Au) bond wire.

CCB #: _____ 2922

Misc.	Assembly site	ASEK
	Part Number (CPN)	KSZ8041TLI-A4-AI-X
Lead-Frame	Paddle size	3.81 mm X 3.81 mm
	Material	C7025
	Surface	Double Ring Ag Plating
	Treatment	N/A
	Process	Stamped
	Lead-lock	None
	Part Number	A08588-0
	Lead Plating	Pure Tin
Bond Wire	Material	Au
Die Attach	Part Number	CRM-1076WA
	Conductive	Yes
MC	Part Number	EME-G631H
PKG	PKG Type	TQFP
	Pin/Ball Count	48
	PKG width/size	7 X 7 X 1.0 mm
Die	Die Thickness	10 mils
	Die Size	1.511 mm X 1.327 mm
	MSL Classification	3

Test Name	Conditions	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	Qty of Lots	Total Units	Fail Accept Qty	Est. Dur. Days	Special Instructions
Standard Pb-free Solderability	JESD22B-102E; Perform 8 hour steam aging for Matte tin finish and 1 hour steam aging for NiPdAu finish prior to testing.	22	5	1	27	> 95% lead coverage	5	Standard Pb-free solderability is the requirement. SnPb solderability (backward solderability- SMD reflow soldering) is required for any plating related changes and highly recommended for other package BOM changes.
Wire Bond Pull - WBP	Mil. Std. 883-2011	5	0	3	24	0 fails after TC	5	30 bonds from a minimum of 5 devices.
Wire Bond Shear - WBS	CDF-AEC-Q100-001	5	0	3	24	0	5	30 bonds from a minimum of 5 devices.
Wire Sweep		5	0	3	15	0		Required for any reduction in wire bond thickness.
External Visual	Mil. Std. 883-2009/2010	All devices prior to submission for qualification testing	0	3	ALL	0	5	
HTSL (High Temp Storage Life)	+175 C for 504 hours or 150°C for 1008 hrs. Electrical test pre and post stress at +25°C and hot temp.85°C, E-test at 85°C only	45	5	1	50	0	10	Must be in progress at time of package release to production, but completion is not required for release to production.
Preconditioning - Required for surface mount devices	+150°C Bake for 24 hours, moisture loading requirements per MSL level + 3X reflow at peak reflow temperature per Jedec-STD-020D for package type; Electrical test pre and post stress at +25°C.	231	15	3	738	0	15	Spares should be properly identified. 77 parts from each lot to be used for HAST, Autoclave, Temp Cycle test.
HAST	+130°C/85% RH for 96 hours or 110°C/85%RH for 264 hours. Electrical test pre and post stress at +25°C and hot temp.	77	5	3	246	0	10	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.

Test Name	Conditions	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	Qty of Lots	Total Units	Fail Accept Qty	Est. Dur. Days	Special Instructions
Unbiased HAST	+130 °C/85% RH for 96 hrs or +110 °C/85% RH for 264 hrs. Electrical test pre and post stress at +25 °C.	77	5	3	246	0	10	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
Temp Cycle	-65 °C to +150 °C for 500 cycles. Electrical test pre and post stress at hot temp; 3 gram force WBP, on 5 devices from 1 lot, test following Temp Cycle stress. E-test at 85 °C only	77	5	3	246	0	15	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.